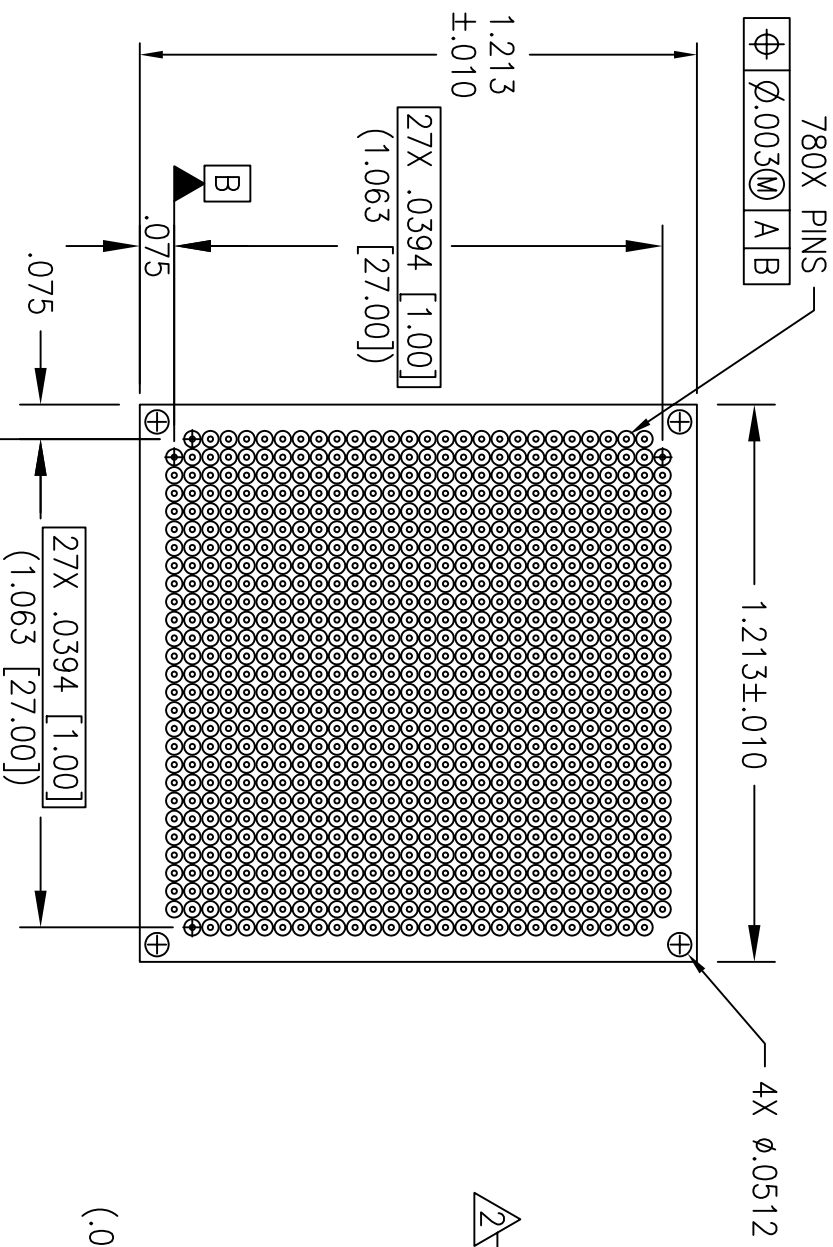
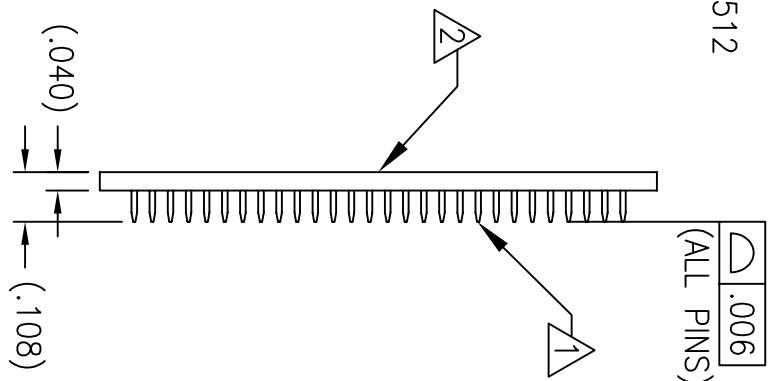


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TOP VIEW



RS VIEW



NOTES:

- 1. PINS  $\Phi .0117$   
MATERIAL: PHOSPHOR BRONZE.  
PLATING: HARD GOLD OVER NICKEL.
- 2. INSULATOR MATERIAL: FR4.

REV	DESCRIPTION	EGN	DATE	RELEASE
1	SALES RELEASE			

CONTRACT NO.		DRAWN BY		DATE		TITLE	
UNLESS OTHERWISE SPECIFIED:		DESIGNER		DATE		HILo-BGA PIN BASE	
DIMENSIONS ARE IN INCHES		CHECKER		DATE		28 X 28, 780 PINS	
TOLERANCES:						1mm PITCH	
ANGLES: ±							
FRACTIONS: 31/64							
DECIMALS: ±.010							
XXX: ±.005							
.XXXX: ±.0005							
PROCESS ENG.		DATE		DATE		SCALE: N/A	
DATE		DATE		DATE		DRAWING NO. HLP-280780-B-10	
DATE		DATE		DATE		FINISHED ASST: HLP-280780-B-10	
DATE		DATE		DATE		SHEET 1 OF 1	

INTERCONNECT SYSTEMS INC.  
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